INTERNATIONAL STANDARD

IEC 61189-2

Second edition
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Test methods for electrical materials, printed boards and other interconnection structures and assemblies –

Part 2: Test methods for materials for interconnection structures

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARDS AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –

Part 2: Test methods for materials for interconnection structures

FOREWORD

1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
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International Standard IEC 61189-2 has been prepared by IEC technical committee 91: Surface mounting technology, in cooperation with technical committee 52: Printed circuits (now disbanded), and technical committee 50: Environmental testing.

This second edition replaces the first edition, published in 1997, and its Amendment 1 (2000). It constitutes a technical revision.

The document 91/564/FDIS, circulated to the National Committees as Amendment 2, led to the publication of this new edition.

The text of this standard is based on the first edition, its amendment 1 and on the following documents:

FDIS	Report on voting
91/564/FDIS	91/572/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

The significant technical changes with respect to the previous edition concern the addition of several new tests in the following categories:

– C: Chemical test methods

– D: Dimensional test methods:

– E: Electrical test methods

– M: Mechanical test methods

– N: Environmental test methods

– X: Miscellaneous test methods

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

This standard forms part of a series and should be used in conjunction with other parts in the same series, all under the main title *Test methods for electrical materials, interconnection structures and assemblies*:

Part 1: General test methods and methodology

Part 2: Test methods for materials for interconnection structures

Part 3: Test methods for interconnection structures (printed boards)

Part 4: Test methods for electronic components assembling characteristics[1]

Part 5: Test methods for printed board assemblies

Part 6: Test methods for materials used in electronic assemblies

It should also be read in conjunction with IEC 60068: Environmental testing.

The committee has decided that the contents of this publication will remain unchanged until the maintenance result date indicated on the IEC web site under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

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1 Under consideration.

INTRODUCTION

IEC 61189 relates to test methods for printed boards and printed board assemblies, as well as related materials or component robustness, irrespective of their method of manufacture.

The standard is divided into separate parts, covering information for the designer and the test methodology engineer or technician. Each part has a specific focus; methods are grouped according to their application and numbered sequentially as they are developed and released.

In some instances test methods developed by other TCs (e.g. TC 50) have been reproduced from existing IEC standards in order to provide the reader with a comprehensive set of test methods. When this situation occurs, it will be noted on the specific test method; if the test method is reproduced with minor revision, those paragraphs that are different are identified.

This part of IEC 61189 contains test methods for materials used to produce interconnection structures (printed boards) and electronic assemblies. The methods are self-contained, with sufficient detail and description so as to achieve uniformity and reproducibility in the procedures and test methodologies.

The tests shown in this standard are grouped according to the following principles:

- P: preparation/conditioning methods
- V: visual test methods
- D: dimensional test methods
- C: chemical test methods
- M: mechanical test methods
- E: electrical test methods
- N: environmental test methods
- X: miscellaneous test methods

To facilitate reference to the tests, to retain consistency of presentation, and to provide for future expansion, each test is identified by a number (assigned sequentially) added to the prefix (group code) letter showing the group to which the test method belongs.

The test method numbers have no significance with respect to an eventual test sequence; that responsibility rests with the relevant specification that calls for the method being performed. The relevant specification, in most instances, also describes pass/fail criteria.

The letter and number combinations are for reference purposes, to be used by the relevant specification. Thus "2D01" represents the first dimensional test method described in this publication.

In short, for this example, 2 is the part of IEC standard (61189-2), D is the group of methods, and 01 is the test number.

A list of all test methods included in this standard, as well as those under consideration is given in Annex B. This annex will be reissued whenever new tests are introduced.

TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARDS AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –

Part 2: Test methods for materials for interconnection structures

1 Scope

This part of IEC 61189 provides a catalogue of test methods representing methodologies and procedures that can be applied to test materials used for manufacturing interconnection structures (printed boards) and assemblies.

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60068-1:1988, *Environmental testing – Part 1: General and guidance*

IEC 60068-2-2:1974, *Environmental testing – Part 2: Tests – Tests B: Dry heat*

IEC 60068-2-78:2001, *Environmental testing – Part 2-78: Tests – Test Cab: Damp heat, steady state*

IEC 60093:1980, *Methods of test for volume resistivity and surface resistivity of solid electrical insulating materials*

IEC 60243-1:1998, *Electrical strength of insulating materials – Test methods: Tests at power frequencies*

IEC 61189-3:1997, *Test methods for electrical materials, interconnection structures and assemblies – Part 3: Test methods for interconnection structures (printed boards)*

ISO 3274:1996, *Geometrical Products Specifications (GPS) – Surface texture: Profile method – Nominal characteristics of contact (stylus) instruments*

ISO 9001:2000, *Quality systems – Model for quality assurance in production, installation and servicing*

ANSI/UL-94:1993, *Standard for tests for flammability of plastic materials for parts in devices and appliances, Tests for*